Claims 1-12 were pending in this application. Claims 1, 3, 8, and 9 have been amended to better define the scope of the claimed invention. Claims 2, 5-7 and 10-12 have been cancelled. New Claims 13-15 have been added.

Claim 12 was objected to. Claim 12 has been amended such that the objection is moot.

Claims 1-12 stand rejected under 35 U.S.C. 103(a) as being unpatentable over Hollingsworth, et al. (U.S. Patent No. 5,521,428). Claim 1, as amended, includes the feature of "a die pad configuration comprising: four separate die pad regions, each of said die pad regions under one of the four corners of said integrated circuit die." Hollingsworth does not teach or suggest such a feature. Therefore, Applicant respectfully submits that Claim 1 is patentable over Hollingsworth. Claims 3 and 4 depend from Claim 1 and are therefore patentable over Hollingsworth for at least the reasons presented above. Claim 8, as amended, includes the feature of a "die pad comprising a support portion for supporting the integrated circuit die, the support portion supporting substantially all of said integrated circuit die, except that corner regions of said die are not supported by said support portion." Hollingsworth does not teach or suggest such a feature. Therefore, Applicant respectfully submits that Claim 8 is patentable over Hollingsworth. Claim 9 depends from Claim 8 and is therefore patentable over Hollingsworth for at least the reasons presented above for that claim. New Claim 13 includes the feature of a "die pad configuration for an integrated circuit including a rectangular integrated circuit die having two long opposing edges and two short opposing edges, the die pad configuration comprising: two separate die pad regions, each of said die pad regions under one of said two long opposing edges of said integrated circuit die." Hollingsworth does not teach or suggest such a feature. Therefore, Applicant respectfully submits that Claim 13 is patentable over Hollingsworth. Claims 14 and 15 depend from Claim 13 and are therefore patentable over Hollingsworth for at least the reasons presented above for that claim.

Applicant respectfully requests reconsideration and withdrawal of the rejections and allowance of Claims 1, 3, 8, 9 and 13-15. If the Examiner has any questions or other correspondence regarding this application, Applicant requests that the Examiner contact Applicant's attorney at the below listed telephone number and address.

Respectfully submitted,

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

In the Claims:

1. (amended) A die pad configuration for an integrated circuit having an integrated circuit die, the die pad configuration comprising:

four separate die pad regions, each of said die pad regions under one of the four corners of said integrated circuit die [a plurality of die pad regions for supporting the integrated circuit die, each die pad region having an area associated therewith, the die pad regions being arranged in a spaced apart relationship with respect to the die, the total area of the plurality of die pad regions being at most equal to fifty percent (50%) of the area of the die].

2. (cancelled)

3. (amended) The die pad configuration of claim 1 wherein the ratio of the total area of the four die pad regions to the die area is in the range of about 0.3 to about 0.5 [2, wherein the four die pad regions are spaced apart such that they are each proximate to a corner of the die].

4. (amended) The die pad configuration of claim 3 wherein the ratio [total area of the four die pad regions] is about 0.32 [of the area of the die].

5. (cancelled)

6. (cancelled)

7. (cancelled)

8. (amended) A die pad for an integrated circuit having an integrated circuit die, the die pad comprising a support portion for supporting the integrated circuit die, the support portion supporting substantially all of said integrated circuit die, except that corner regions of said die are not supported by said support portion [having a plurality of regions of relief therein, the relief regions being arranged in a spaced apart relationship with respect to the die, the support portion having a total area being at most equal to forty percent (40%) of the area of the die].

9. (amended) The die pad of claim 8, wherein the ratio of the area of the support portion of the die pad to the area of the die is in the range of about 0.3 to about 0.5 [plurality of relief regions include four rectangular regions].

10. (cancelled)

11. (cancelled)

12. (cancelled)

Please add the following new claims:

13. (new) A die pad configuration for an integrated circuit including a rectangular integrated circuit die having two long opposing edges and two short opposing edges, the die pad configuration comprising:

two separate die pad regions, each of said die pad regions under one of said two long opposing edges of said integrated circuit die.

14. (new) The die pad configuration of claim 13 wherein the ratio of the total area of the two die pad regions is in the range of about 0.40 to about 0.50.

15. (new) The die pad configuration of claim 14 wherein the ratio is about 0.42.